

REMARKS

Claims 1-10 were pending prior to the above amendments. Claim 10 is canceled.

Claims 1-2, 5 and 9 are amended. Claim 11 is newly presented. No new matter is introduced.

As amended, Claim 1 now recites:

a plurality of elongated leads... each of said elongated leads including a circular portion formed as an attachment pad;

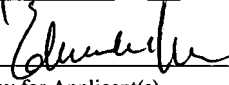
... a substrate, having first and second surfaces on opposite sides of said substrate, for providing rigid support to said lead frame, said substrate contacting said lead frame on said first surface and having vias of non-circular cross sections to allow electrical connections between said first and second surfaces;

(emphasis added)

As discussed in Applicants' Specification, at page 6, lines 11-19, the circular attachment pads allows the use of non-circular vias that can be formed without the difficulties in the prior art of forming circular vias, and thus resulting in consistent post-installation solder ball profiles. Since neither the circular pads and the vias of non-circular cross sections nor their attendant benefits are disclosed or suggested by Mizobe (Japanese patent publication 3-166756) or Barrow (U.S. Patent 5,796,589), Applicants believe that Claim 1 and its dependent Claims 2-8 and 11 are each patentable over Mizobe, Barrow or their combination. Since Claim 9 also recite similar limitations, Claim 9 is also patentable over Mizobe and Barrow, individually or in combination.

Thus, the Examiner's rejections of Claims 1-4 and 8 under 35 U.S.C. § 102(b) over Mizobe, Claims 5-7 under 35 U.S.C. § 103(a) over Mizobe in view of Barrow, and Claim 9 under 35 U.S.C. § 103(a) over Mizobe are believed overcome.

Reconsideration and allowance of all pending claims (i.e., Claims 1-9 and 11) are respectfully sought. If the Examiner has any questions regarding the above, the Examiner is respectfully requested to telephone the undersigned Attorney for Applicants at 408-453-9200.

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Respectfully submitted,



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